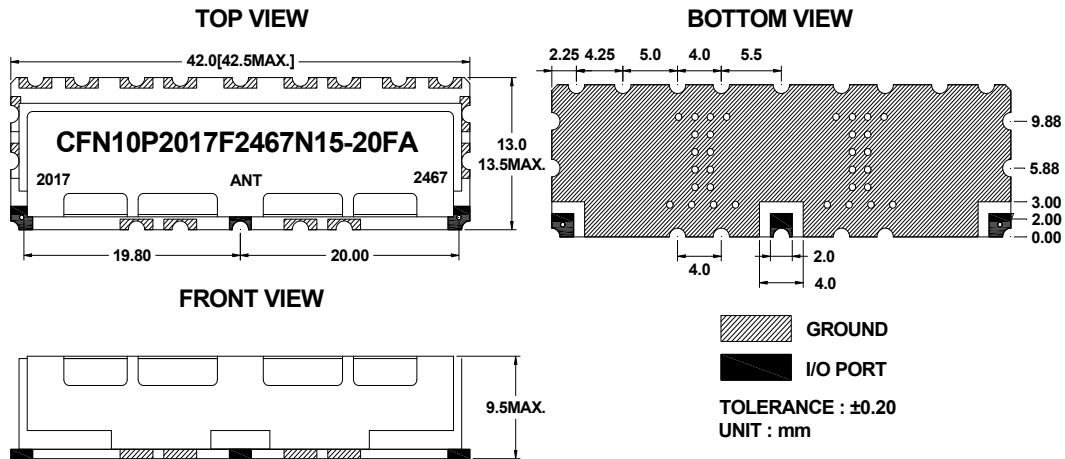


Electrical Specification

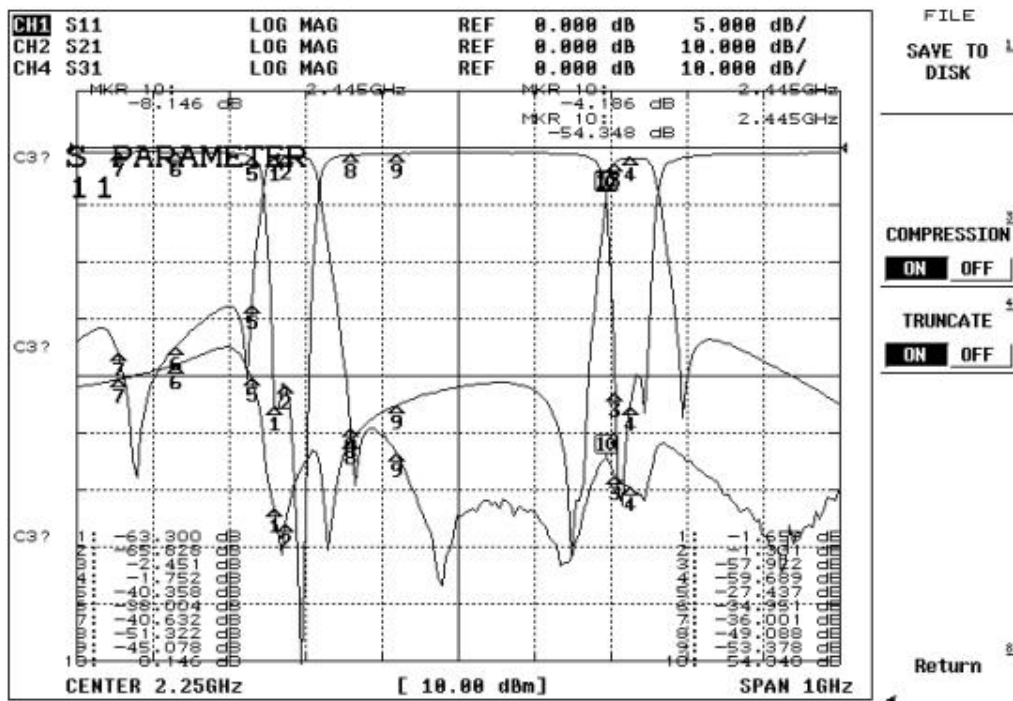
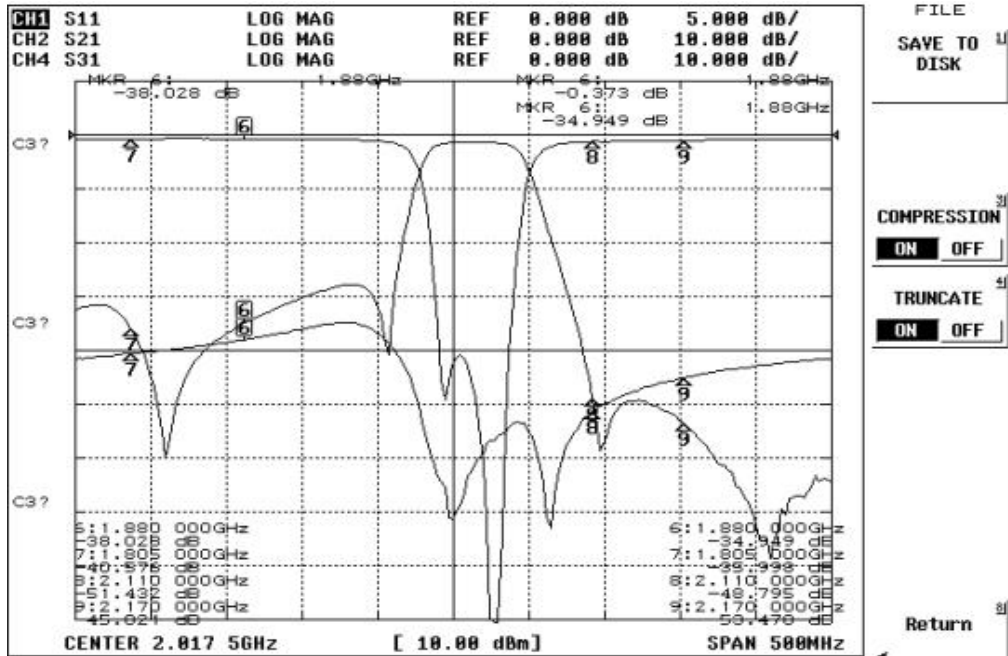
ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	2017.5	2467.0	MHz
Bandwidth [BW]	fo ±7.5 [2010.0~2025.0]	fo ±10 [2457.0~2477.0]	MHz
Insertion Loss in BW	2.5	2.8	dB max
Ripple in BW	1.0	1.0	dB max
Return Loss in BW			dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	55.0 dBmin. @ [2457~2477]	60.0 dBmin. [2010~2025]	MHz
	45 dBmin. @ [2110~2170]	8.0 dBmin. [2400~2445]	MHz
	25 dBmin. @ [1920~1980]	42 dBmin. @ [2110~2170]	MHz
	34 dBmin. @ [1805~1880]	32dBmin. @ [1920~1980]	MHz
	dBmin. @ [~]	35dBmin. @ [1805~1880]	
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

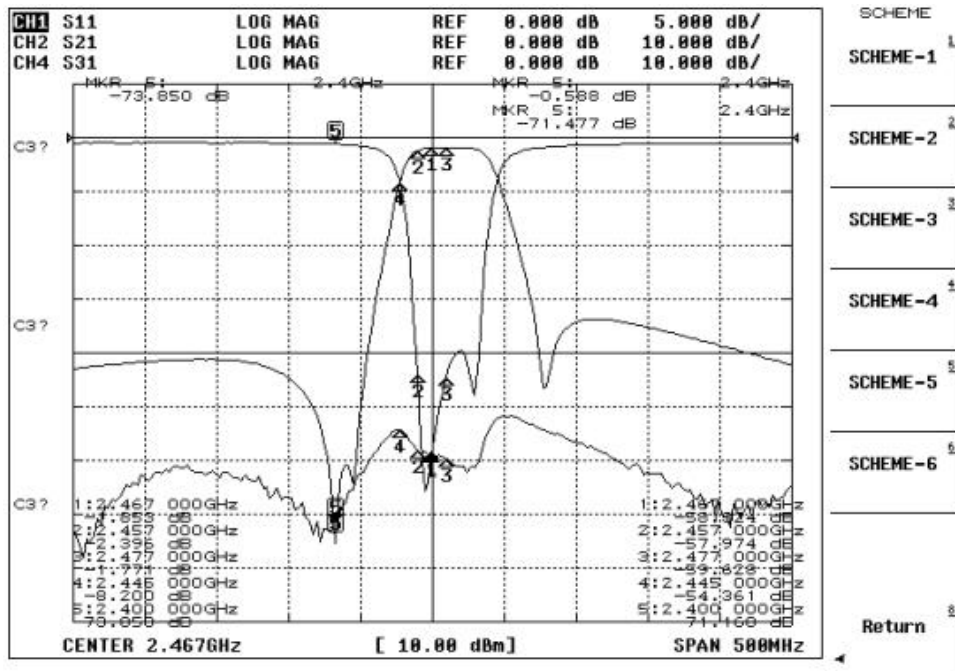
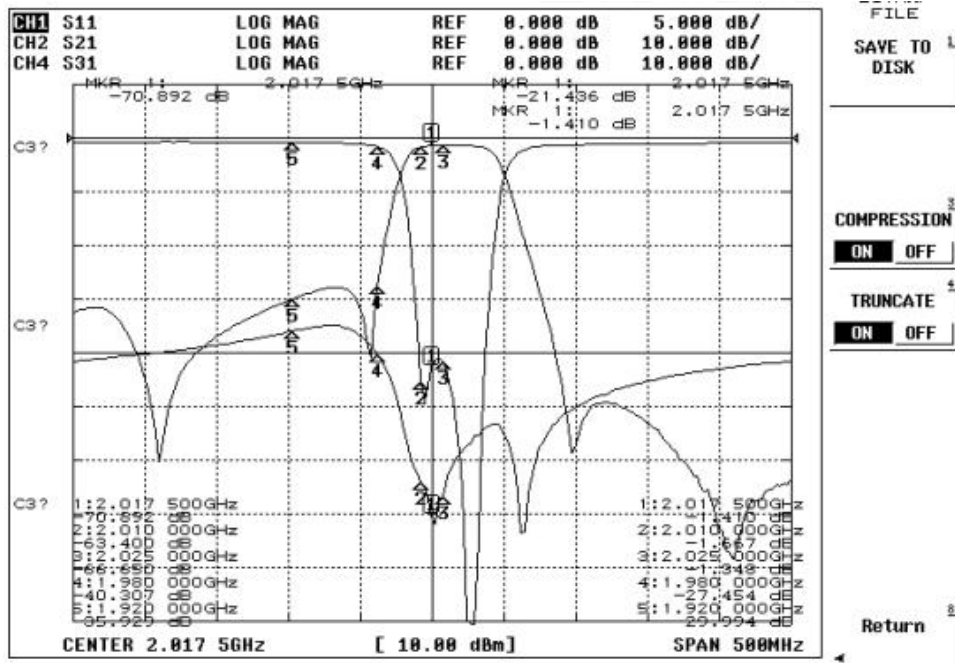
Mechanical Specification



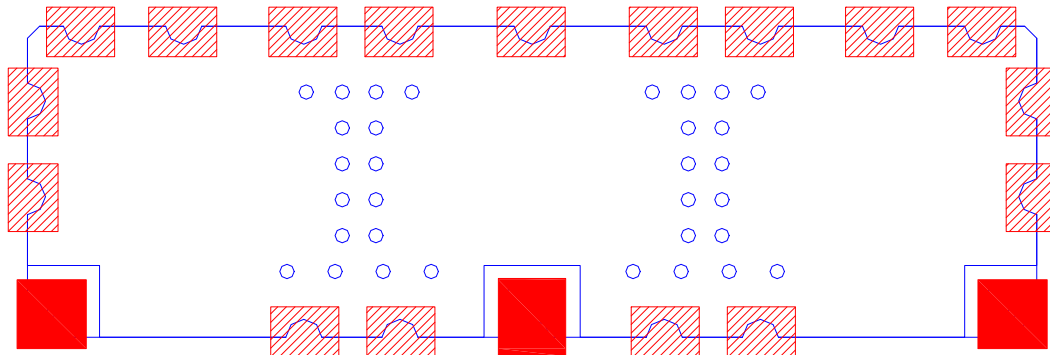


Plot Data



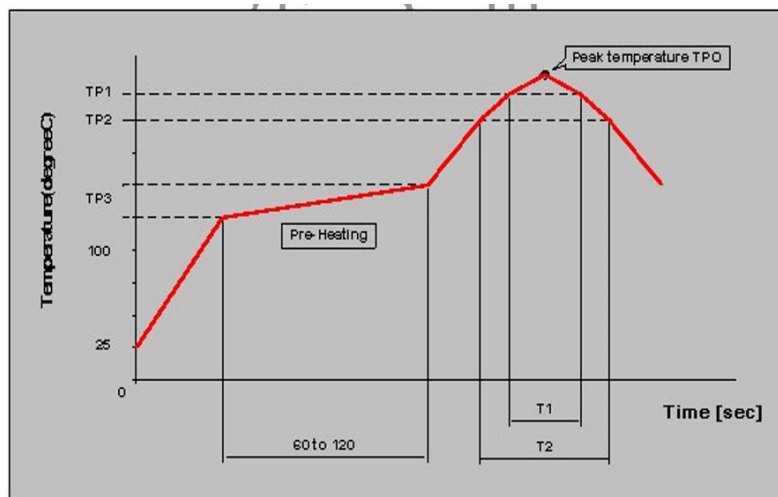


Recommneded PC Board Pattern



 **I/O PORT SOLDERING POINT**
 **GROUND SOLDERING POINT**

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180